

Title (en)

Apparatus for the placement and bonding of a die on a substrate

Title (de)

Gerät zum Positionieren und zum Verbinden einer Komponenten auf einem Substrat

Title (fr)

Appareil pour le placement et le montage d'un composant sur un substrat

Publication

**EP 1174909 A3 20050126 (EN)**

Application

**EP 01306036 A 20010713**

Priority

US 61832400 A 20000718

Abstract (en)

[origin: EP1174909A2] An apparatus (10) and method for the placement and bonding of a die (26) on a substrate (48) includes a movable die holder (24), a movable substrate holder (42), a pivoting transfer arm (30) that picks a die (26) from the movable die holder (24) and transfers the die (26) to a position adjacent the movable substrate holder (42), and a bondhead assembly (16) for picking the die (26) from the transfer arm (30) and then bonding the die (26) to the substrate (48). <IMAGE>

IPC 1-7

**H01L 21/00**; H05K 13/04

IPC 8 full level

**H01L 21/00** (2006.01)

CPC (source: EP US)

**H01L 21/67144** (2013.01 - EP US); **H01L 24/75** (2013.01 - EP US); **H01L 24/81** (2013.01 - EP US); **Y10T 29/49133** (2015.01 - EP US); **Y10T 29/53091** (2015.01 - EP US); **Y10T 29/53178** (2015.01 - EP US); **Y10T 29/53261** (2015.01 - EP US)

Citation (search report)

- [A] EP 0487336 A2 19920527 - IBM [US]
- [A] US 5667129 A 19970916 - MORITA KOICHI [JP], et al
- [A] US 5579980 A 19961203 - ICHIKAWA SHIGERU [JP]

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US11232960B2; CN107658255A; EP1775753A3; WO2005111554A3; WO2005111554A2; US7472031B2

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

**EP 1174909 A2 20020123**; **EP 1174909 A3 20050126**; US 6640423 B1 20031104

DOCDB simple family (application)

**EP 01306036 A 20010713**; US 61832400 A 20000718